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TID #: TIDA-01518

TIDA-01518 REV A Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB	1		TIDA-01518	Any	Printed Circuit Board	
2	BT1	1		BAT-HLD-001	Linx Technologies	Battery Holder, Retainer clip, SMT	22.9x4.2x15.5mm
3	BUZZ, DRDY, GND, GND, LEAK, POW, SCL, SDA	8	SMT	5015	Keystone	Test Point, Miniature, SMT	Testpoint_Keystone_Miniature
4	BUZZER	1		CEP-1112	CUI Inc.	Piezo Audio Transducer, TH	D24xH7.3mm
5	C1	1	4700pF	06031C472JAT2A	AVX	CAP, CERM, 4700 pF, 100 V,+/- 5%, X7R, 0603	0603
6	C2	1	1uF	06033C105KAT2A	AVX	CAP, CERM, 1 µF, 25 V,+/- 10%, X7R, 0603	0603
7	C3	1	100uF	C3216X5R1A107M160AC	TDK	CAP, CERM, 100 µF, 10 V, +/- 20%, X5R, 1206_190	1206_190
8	C4, C6, C7	3	330uF	T495C337K004ATE700	Kemet	CAP, TA, 330 µF, 4 V, +/- 10%, 0.7 ohm, SMD	6032-28
9	C5	1	10uF	0805YD106KAT2A	AVX	CAP, CERM, 10 µF, 16 V,+/- 10%, X5R, 0805	0805
10	C8	1	0.01uF	06031C103JAT2A	AVX	CAP, CERM, 0.01 µF, 100 V,+/- 5%, X7R, 0603	0603
11	C9	1	0.1uF	GCM21BR71H104KA37K	MuRata	CAP, CERM, 0.1 µF, 50 V,+/- 10%, X7R, AEC-Q200 Grade 1, 0805	0805
12	C31	1	0.1uF	GCM155R71H104KE02D	MuRata	CAP, CERM, 0.1 µF, 50 V,+/- 10%, X7R, AEC-Q200 Grade 1, 0402	0402
13	CURRENT, POW_2_LEAK, POW_2_TEMP, POWER	4		61300211121	Wurth Elektronik	Header, 2.54 mm, 2x1, Gold, TH	Header, 2.54mm, 2x1, TH
14	D_ESD	1		TPD1E10B06DPYR	Texas Instruments	ESD in 0402 Package with 10 pF Capacitance and 6 V Breakdown, 1 Channel, -40 to +125 degC, 2-pin X2SON (DPY), Green (RoHS & no Sb/Br)	DPY0002A
15	L1	1	47mH	RLB0913-473K	Bourns	Inductor, Wirewound, Ferrite, 47 mH, .03 A, 99 ohm, TH	D8.5xL12.5mm
16	LEFT, RIGHT	2		SSQ-110-03-T-D	Samtec	Receptacle, 2.54mm, 10x2, Tin, TH	10x2 Receptacle
17	Q1, Q2	2	60 V	MMBT2907ALT1G	ON Semiconductor	Transistor, PNP, 60 V, 0.6 A, SOT-23	SOT-23
18	Q3	1	-20V	SI2323DS	Vishay-Siliconix	MOSFET, P-CH, -20 V, -3.7 A, SOT-23	SOT-23
19	R1, R2	2	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
20	R3	1	330	CRCW1206330RJNEA	Vishay-Dale	RES, 330, 5%, 0.25 W, 1206	1206
21	R4	1	20k	CRCW060320K0JNEA	Vishay-Dale	RES, 20 k, 5%, 0.1 W, 0603	0603
22	R5, R7	2	560k	CRCW0603560KJNEA	Vishay-Dale	RES, 560 k, 5%, 0.1 W, 0603	0603
23	R6	1	5.6k	CRCW06035K60JNEA	Vishay-Dale	RES, 5.6 k, 5%, 0.1 W, 0603	0603
24	R8	1	10.2	CMF5010R200FHEB	Vishay-Dale	RES, 10.2, 1%, 0.25 W, Axial	Axial
25	R9	1	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
26	R19	1	330k	CRCW0402330KJNED	Vishay-Dale	RES, 330 k, 5%, 0.063 W, 0402	0402
27	SH-J1, SH-J2, SH-J3, SH-J4	4	1x2	2SN-BK-G	Samtec	Shunt, 2mm, Gold plated, Black	2mm Shunt, Closed Top
28	U1	1		HDC2010YPAR	Texas Instruments	HDC2010 Low Power Humidity and Temperature Digital Sensor, YPA0006ABAB (DSBGA-6)	YPA0006ABAB
29	Water_Probe	1		22-27-2021	Molex	Header (friction lock), 100mil, 2x1, Tin, TH	Header, 2x1, 100mil, TH

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